

AMENDMENTS TO THE CLAIMS

Claim 1 (Previously Presented): A pressure sensor including

- a semiconductor device capable of detecting pressure;
- a bonding wire;
- a terminal that is connected to the semiconductor device by the bonding wire;
- a housing having an accommodation space accommodating the semiconductor device,

the bonding wire and the terminal;

- a diaphragm sealing the accommodation space; and
- a working fluid that is sealed in the accommodation space and transmits pressure

applied to the diaphragm to the semiconductor device, wherein

- the working fluid is a silicone-based oil; and
- the terminal and the housing are sealed by a fluorine-based adhesive.

Claim 2 (Previously Presented): A pressure sensor including

- a semiconductor device capable of detecting pressure;
- a bonding wire;
- a terminal that is connected to the semiconductor device by the bonding wire; and
- a housing having an accommodation space accommodating the semiconductor device,

the bonding wire and the terminal, wherein

- the terminal and the housing are sealed by a fluorine-based adhesive.

Claim 3 (Original): The pressure sensor according to claim 1, wherein the fluorine-based adhesive is a perfluoro polyether resin composition.

Claim 4 (Original): The pressure sensor according to claim 2, wherein the fluorine-based adhesive is a perfluoro polyether resin composition.

Claim 5 (Previously Presented): The pressure sensor according to claim 2, wherein the pressure sensor does not include a working fluid.

Claim 6 (Previously Presented): A method of making a pressure sensor including a semiconductor device capable of detecting pressure; a bonding wire; a terminal that is connected to the semiconductor device by the bonding wire; a housing having an accommodation space accommodating the semiconductor device, the bonding wire and the terminal; a diaphragm sealing the accommodation space; and a working fluid that is sealed in the accommodation space and transmits pressure applied to the diaphragm to the semiconductor device, where the working fluid is a silicone-based oil; and the terminal and the housing are sealed by a fluorine-based adhesive, the method comprising
sealing the terminal and the housing with the fluorine-base adhesive; and
producing the pressure sensor of claim 1.

Claim 7 (Previously Presented): A method of making a pressure sensor including a semiconductor device capable of detecting pressure; a bonding wire; a terminal that is connected to the semiconductor device by the bonding wire; and a housing having an accommodation space accommodating the semiconductor device, the bonding wire and the terminal, where the terminal and the housing are sealed by a fluorine-based adhesive, the method comprising

sealing the terminal and the housing with the fluorine-based adhesive; and
producing the pressure sensor of claim 2.

REQUEST FOR RECONSIDERATION

Claims 1-7 are pending in this application. Claims 1 and 2 are independent.

Claims 1-7 are rejected under 35 U.S.C. § 103(a) over U.S. Patent No. 6,813,953 ("Baba") in view of U.S. Patent No. 5,689,089 ("Polak"). Applicants respectfully traverse the rejection because Baba is not prior art to the above-identified application. Baba was filed on April 21, 2003. In contrast, the above-identified application is entitled to the priority of Japanese Application No. 2002-364414 ("JP-414") of December 16, 2002. To perfect Applicants' claim to priority under 37 C.F.R. § 1.55(a)(4), attached is an English-language translation of the JP-414 priority document, along with a certification from the translator. Because the priority date of the above-identified application is prior to the filing date of Baba, Baba is not prior art to the above-identified application. Thus, the rejection under 35 U.S.C. § 103(a) should be withdrawn.

Pursuant to M.P.E.P. § 821.04, after independent product Claims 1-2 are allowed, Applicants respectfully request examination and allowance of method Claims 6-7, which include all of the limitations of product Claims 1-2, respectively.

In view of the foregoing amendments and remarks, Applicants respectfully submit that the application is in condition for allowance. Applicants respectfully request favorable consideration and prompt allowance of the application.

Should the Examiner believe that anything further is necessary in order to place the application in even better condition for allowance, the Examiner is invited to contact Applicants' undersigned attorney at the telephone number listed below.

Respectfully submitted,

OBLON, SPIVAK, McCLELLAND,
MAIER & NEUSTADT, P.C.
Norman F. Oblon



Corwin P. Umbach, Ph.D.
Registration No. 40,211

Attached:

English-language translation of Japanese Application No. 2002-364414
Translator's Certification

Customer Number

22850

Tel: (703) 413-3000
Fax: (703) 413 -2220
(OSMMN 06/04)

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